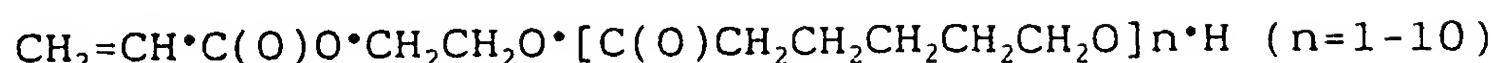


WHAT IS CLAIMED IS:

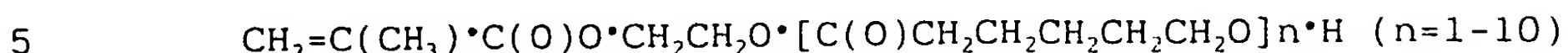
1. A sheet-form, curable pressure-sensitive adhesive comprising a composition including:
 - (A) a high molecular weight polymer;
 - 5 (B) a compound containing an epoxy group; and
 - (C) a polymerization initiator which, when an activation energy is applied thereto, initiates the compound (B) to undergo a ring-opening polymerization.
- 10 2. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 1, wherein said high molecular weight polymer (A) is an acrylic polymer.
- 15 3. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 1, wherein said composition comprises 100 parts by weight of an acrylic polymer (A), 1 - 10000 parts by weight of the compound (B) and 0.01 - 1000 parts by weight of the polymerization initiator (C).
- 20 4. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 2, wherein the acrylic polymer (A) is a copolymer obtainable by copolymerizing a compound (a) containing at least one (meth)acryloyl group and at least one hydroxyl group per molecule with a copolymerizable monomer (b) which is copolymerizable with the compound (a).
- 25 5. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 4, wherein said compound (a) is at least one selected from the group consisting of the

following compounds (1) through (10):

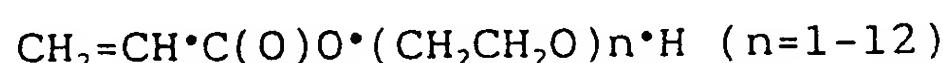
[Compound 1]



[Compound 2]



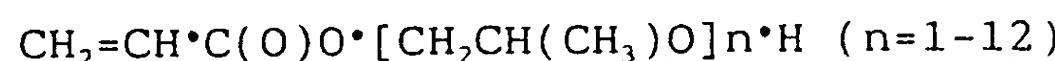
[Compound 3]



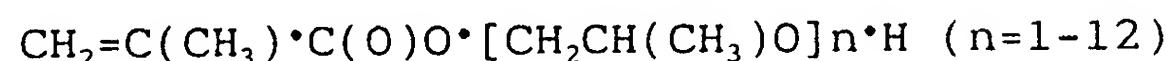
[Compound 4]



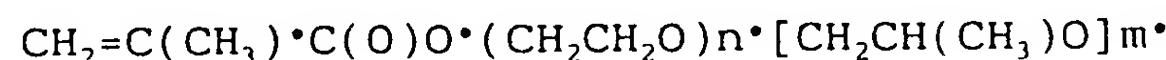
10 [Compound 5]



[Compound 6]



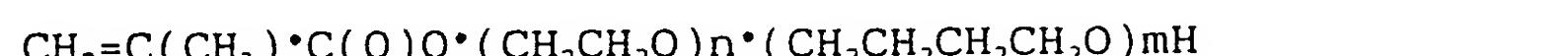
[Compound 7]



(n=1-12, m=1-10)

【Compound 8】

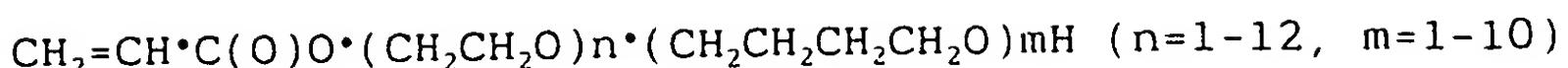
(Compound 9)



$$\text{CH}_2=\text{C}(\text{CH}_3)\bullet\text{C(O)O}\bullet(\text{CH}_2\text{CH}_2\text{O})_n\bullet(\text{CH}_2\text{CH}_2\text{CH}_2\text{CH}_2\text{O})_m\text{H}$$

(n=1-12, m=1-10)

[Compound 10]



6. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 4, wherein said copolymerizable monomer (b) is selected from the group consisting of methyl (meth)acrylate, ethyl (meth)acrylate, cyclohexyl (meth)acrylate, benzyl (meth)acrylate and (meth)acrylic acid ester of alcohols containing a C-O-C ether bond.

7. The sheet-form, curable pressure-sensitive adhesive in accordance with any one of the preceding claims 1-6, wherein said polymerization initiator (C) is cationic photopolymerization initiator.

8. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 7, wherein said cationic photopolymerization initiator is an onium salt compound.

9. The sheet-form, curable pressure-sensitive adhesive in accordance with any one of the preceding claims 1-8, wherein said composition further comprises a vinyl ether compound.

10. The sheet-form, curable pressure-sensitive adhesive in accordance with claim 9, said composition includes 1-30 parts by weight of the vinyl ether compound relative to 30-70 parts by weight of the compound (B).

11. A curable pressure-sensitive adhesive sheet comprising:

a substrate; and

a sheet-form, curable pressure-sensitive adhesive in accordance with any one of the preceding claims 1-10 which is laminated onto at least one surface of said substrate.

5 12. A method for joining members comprising the steps

of:

placing a sheet-form, curable pressure-sensitive adhesive in accordance with any one of preceding claims 1-10 on one of said members; and

10 irradiating the sheet-form, curable pressure-sensitive adhesive with an ultraviolet light having an intensity greater than 1 mW/cm^2 in a wavelength range exceeding 300 nm, either before or after said one member is adhered to another member via the sheet-form, curable pressure-sensitive adhesive.

15 13. An energy polymerizable composition which is pressure-sensitive in its ordinary state and is capable of being cured upon application of an activation energy thereto, said composition comprising:

20 (A) a high molecular weight polymer;

(B) a compound containing an epoxy group; and

(C) a polymerization initiator which, when said activation energy is applied thereto, initiates the compound (B) to undergo a ring-opening polymerization.